

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

Jeong-sic JEON, et al.

Serial No. 10/003,412

Filed: December 6, 2001

For: APPARATUS FOR MANUFACTURING  
SEMICONDUCTOR DEVICE



Notice of Allowance Mailed:  
March 25, 2004

Art Unit: 1763

Examiner: Parviz HASSANZADEH

Confirmation No. 5396

**AMENDMENT UNDER 37 C.F.R. § 1.312**

Mail Stop: ISSUE FEE

Commissioner for Patents

United States Patent and Trademark Office

Alexandria, VA 22313-1450

Sir:

**INTRODUCTORY COMMENT**

It is respectfully requested that the above-referenced application be returned to the Examiner for consideration and entry of the following amendment:

**IN THE SPECIFICATION**

Kindly amend the specification as follows:

Page 13, paragraph [0035]

[0035] For a wafer 30 shown in Fig. 1A having a diameter identical to the diameter M3 of the wafer 130 shown in Fig. 2, the diameter M1 of the insulating plate 120 shown in Fig. 2 would preferably be larger than the diameter L1 of an insulating plate 20 in Fig. 1A 2. Thus, the distance spanned by the plurality of induction coils 114 shown in Fig. 2 would be greater than distance spanned by the plurality of induction coils 14 shown in Fig. 1A.